





















\$pring 2016















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Environmental Constraints						
Company National Somiconductor		National Semiconductor	URL for Additional Information			1
		The Sight & Sound of Information	nup.//www.national.com/quality/green/			<u>/</u>
Contact		Title	Phone	Email		
Gloria Gordon	Engineer	ing Project Manager	1-408-721-8435	1-8435 <u>Green.project@nsc.com</u>		
Part Number		MSL Rating	Peak Body Temp C	MaxTime (Sec)	Cycles	
LM2578AM		1	235	30	4	
Document Date	contains Lead	d(Pb) and is NOT Europ	ean RoHS Complian	Weight (mg)	Unit Type	
18-Aug-2007	1	NOT China RoHS Cor	mpliant .	70.000	Each	
Homogeneous Material Composition Declaration for Electronic Products						
ltem	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Plastic	44.710	SiO2	60676-86-0	36.215	810,000	517,359
		Epoxy Resin	25928-94-3	7.243	162,000	103,472
		Sb2O3	1309-64-4	0.894	20,000	12,774
		Brominated Epoxy	40039-93-8	0.358	8,000	5,110
Leadframe	20.560	Cu	7440-50-8	20.036	974,500	286,225
		Fe	7439-89-6	0,493	24,000	7,049
		Zn	7440-66-6	0.025	1,200	352
		Р	7723-14-0	0.006	300	88
Chip	2.360	Si	7440-21-3	2.346	994.000	33.512
		AI	7429-90-5	0.014	6,000	202
Ext. LeadFinish	1.840	Sn	7440-31-5	1.564	850,000	22,343
		Pb	7439-92-1	0.276	150,000	3,943
Die Attach	0.270	Ag	7440-22-4	0.203	750,000	2,893
		Epoxy Resin	25928-94-3	0.068	250,000	964
Int. LeadFinish	0.180	Ag	7440-22-4	0.180	1,000,000	2,571
Wires	0.080	Au	7440-57-5	0.080	1,000,000	1,143
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Manufacturing Constraints

- Reduce the number of parts
- Standardize and use common parts
- Design such that parts only assemble one-way
- Design parts with tapers and chamfers
- Design parts that can be guided and automatically fed
- Avoid large heavy parts or small, fragile parts
- Eliminate fasteners where possible (snap-fitting)
- Standardize fasteners
- Provide modular designs (subassemblies) Spring 2016





